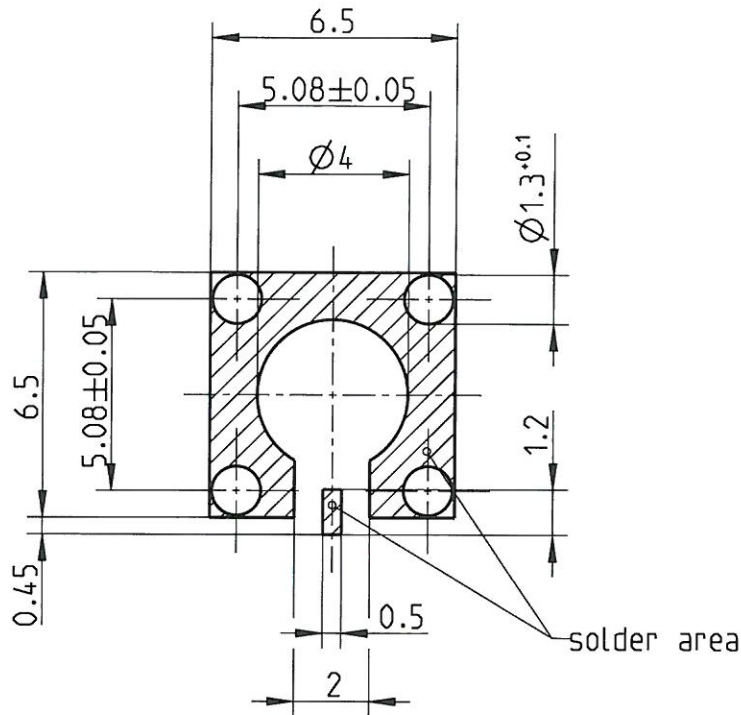


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Leiterplatten-Layout  
PCB layout  
B 122



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formidat: TCC-FB-05-PL-AK-Einzelteil  
Datei: A:\Pse-config\04mm\...\_E08.RBR  
Version: 1.1

ISO-Projektion  
Methode E  
-METRIC-

<b>Rosenberger</b> Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER			general tolerance ISO 2768 RN 006-01 m-H dimensions <0.5 and symmetry		scale: 5:1 weight[g]: surface[mm <sup>2</sup> ]:
			date name drawn 02.06.2003 T_Schmid check. 10.05.06 WY appr. 10.05.06 Krautwille dimensioning incl. finish		title: <b>Leiterplatten-Layout PCB layout</b>
b00	06-0194	S_Krautenbac	26.04.2006	drawing-no.: MB_122 sheet: 1	
a00	00-0000	A_Nobis	15.10.2003	of: 1	
rev.	change-no	name	date	distribu- tion to:	FE AZ QSM RMT . X . . . . remarks: .

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